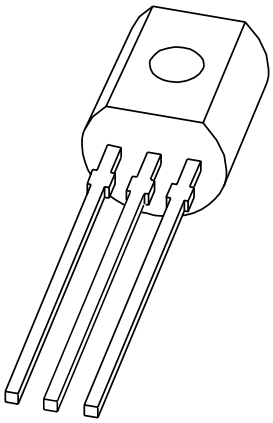
DATA SHEET



BC549; BC550
NPN general purpose transistors

Product specification
Supersedes data of 1999 Apr 22

2004 Oct 11

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NPN general purpose transistors BC549; BC550

FEATURES

- Low current (max. 100 mA)
- Low voltage (max. 45 V).

APPLICATIONS

- Low noise stages in audio frequency equipment.

DESCRIPTION

NPN transistor in a TO-92; SOT54 plastic package.
PNP complements: BC559 and BC560.

PINNING

PIN	DESCRIPTION
1	emitter
2	base
3	collector

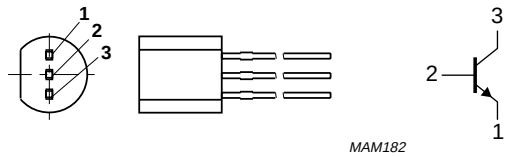


Fig.1 Simplified outline (TO-92; SOT54) and symbol.

ORDERING INFORMATION

TYPE NUMBER	PACKAGE		
	NAME	DESCRIPTION	VERSION
BC549C	SC-43A	plastic single-ended leaded (through hole) package; 3 leads	SOT54
BC550C			

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{CBO}	collector-base voltage	open emitter			
	BC549		–	30	V
	BC550		–	50	V
V_{CEO}	collector-emitter voltage	open base			
	BC549		–	30	V
	BC550		–	45	V
V_{EBO}	emitter-base voltage	open collector	–	5	V
I_C	collector current (DC)		–	100	mA
I_{CM}	peak collector current		–	200	mA
I_{BM}	peak base current		–	200	mA
P_{tot}	total power dissipation	$T_{amb} \leq 25$ °C; note 1	–	500	mW
T_{stg}	storage temperature		–65	+150	°C
T_j	junction temperature		–	150	°C
T_{amb}	ambient temperature		–65	+150	°C

Note

1. Transistor mounted on an FR4 printed-circuit board.

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th(j-a)}$	thermal resistance from junction to ambient	note 1	250	K/W

Note

1. Transistor mounted on an FR4 printed-circuit board.

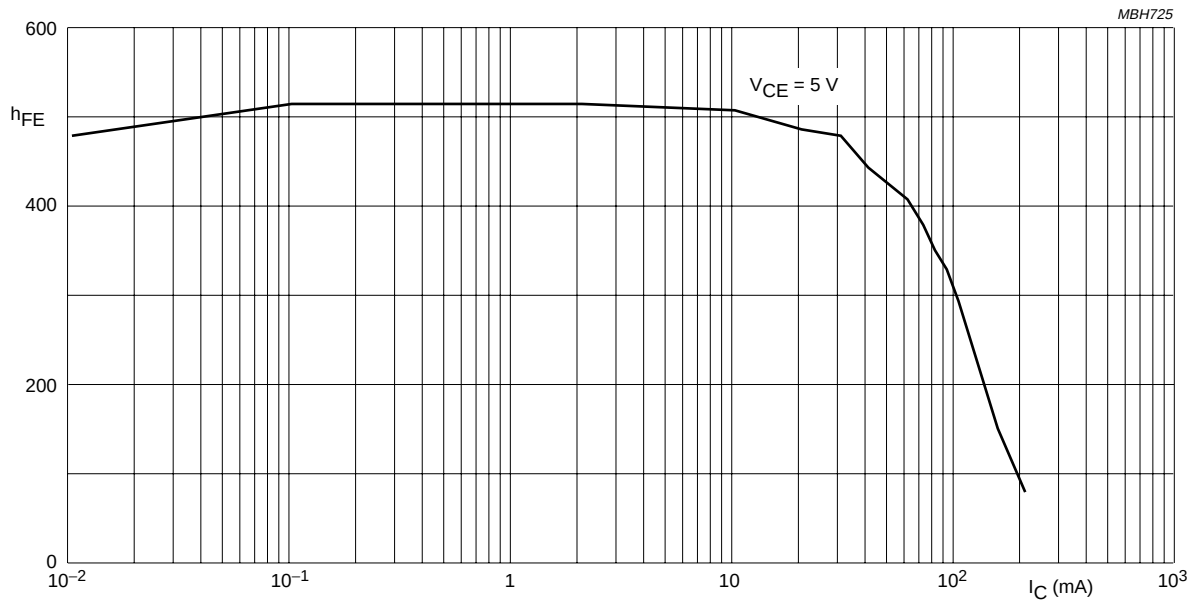
CHARACTERISTICS

T_{amb} = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I_{CBO}	collector-base cut-off current	V_{CB} = 30 V; I_E = 0 A	–	–	15	nA
		V_{CB} = 30 V; I_E = 0 A; T_j = 150 °C	–	–	5	μA
I_{EBO}	emitter-base cut-off current	V_{EB} = 5 V; I_C = 0 A	–	–	100	nA
h_{FE}	DC current gain	V_{CE} = 5 V; see Fig.2				
		I_C = 10 μA	–	270	–	
		I_C = 2 mA	420	520	800	
V_{CEsat}	collector-emitter saturation voltage	I_C = 10 mA; I_B = 0.5 mA	–	90	250	mV
		I_C = 100 mA; I_B = 5 mA	–	200	600	mV
V_{BEsat}	base-emitter saturation voltage	I_C = 10 mA; I_B = 0.5 mA; note 1	–	700	–	mV
		I_C = 100 mA; I_B = 5 mA; note 1	–	900	–	mV
V_{BE}	base-emitter voltage	V_{CE} = 5 V; I_C = 2 mA; note 2	580	660	700	mV
		V_{CE} = 5 V; I_C = 10 mA; note 2	–	–	770	mV
C_c	collector capacitance	V_{CB} = 10 V; I_E = i_e = 0 A; f = 1 MHz	–	1.5	–	pF
C_e	emitter capacitance	V_{EB} = 0.5 V; I_C = i_c = 0 A; f = 1 MHz	–	11	–	pF
f_T	transition frequency	V_{CE} = 5 V; I_C = 10 mA; f = 100 MHz	100	–	–	MHz
F	noise figure	V_{CE} = 5 V; I_C = 200 μA; R_S = 2 kΩ; f = 10 Hz to 15.7 kHz	–	–	4	dB
		V_{CE} = 5 V; I_C = 200 μA; R_S = 2 kΩ; f = 1 kHz; B = 200 Hz	–	–	4	dB

Notes

1. V_{BEsat} decreases by about 1.7 mV/K with increasing temperature.
2. V_{BE} decreases by about 2 mV/K with increasing temperature.

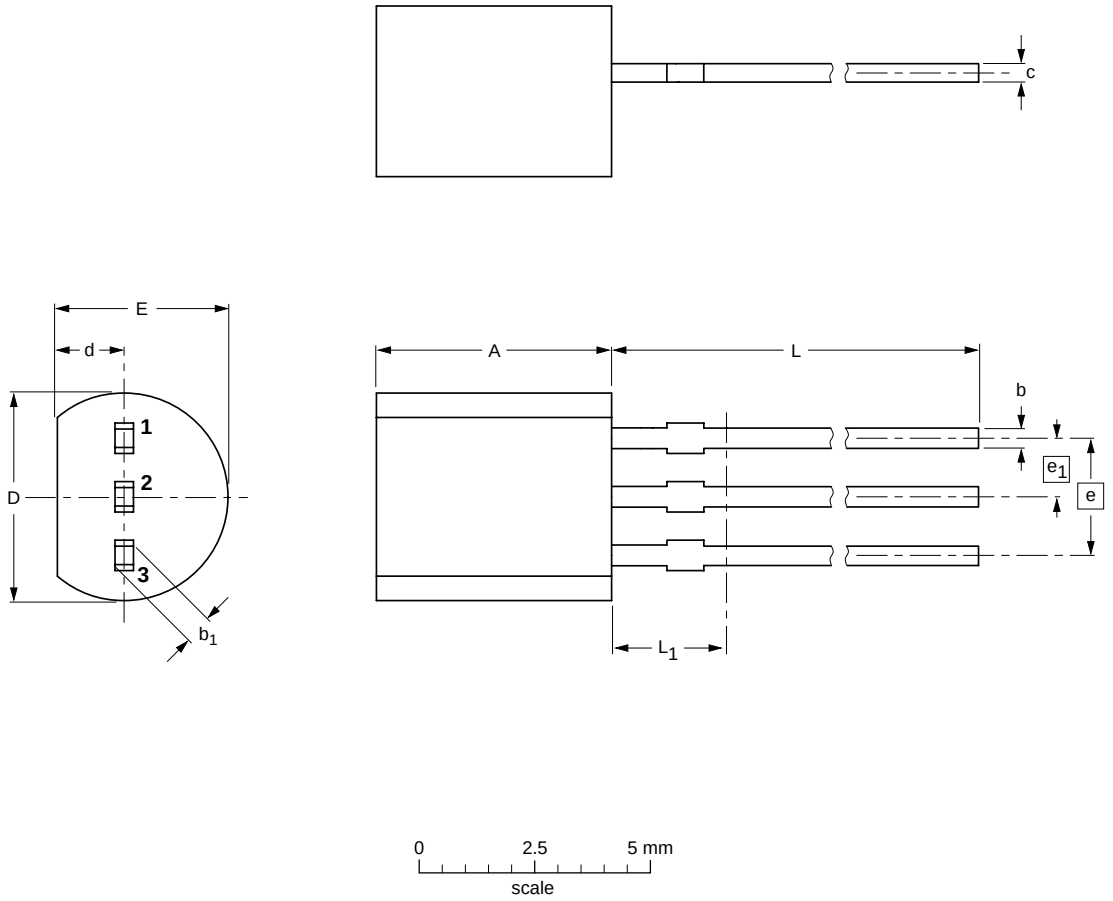


BC549C; BC550C.

Fig.2 DC current gain; typical values.

PACKAGE OUTLINE

Plastic single-ended leaded (through hole) package; 3 leads **SOT54**



DIMENSIONS (mm are the original dimensions)

UNIT	A	b	b_1	c	D	d	E	e	e_1	L	L_1(1) max.
mm	5.2 5.0	0.48 0.40	0.66 0.55	0.45 0.38	4.8 4.4	1.7 1.4	4.2 3.6	2.54	1.27	14.5 12.7	2.5

Note

1. Terminal dimensions within this zone are uncontrolled to allow for flow of plastic and terminal irregularities.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT54		TO-92	SC-43A			~~97-02-28~~ 04-06-28

DATA SHEET STATUS

LEVEL	DATA SHEET STATUS(1)	PRODUCT STATUS(2)(3)	DEFINITION
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